INTEGRATED CIRCUITS

DATA SHEET

FBL2031

9-bit BTL 3.3V latched/registered/pass-thru Futurebus+ transceiver

Product specification Supersedes data of 1998 Sep 04





9-bit BTL 3.3V latched/registered/pass-thru Futurebus+ transceiver

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FEATURES

- Latched, registered or straight through in either A to B or B to A path
- Drives heavily loaded backplanes with equivalent load impedances down to 10 Ω .
- High drive 100mA BTL open collector drivers on B-port
- Allows incident wave switching in heavily loaded backplane buses
- Reduced BTL voltage swing produces less noise and reduces power consumption
- Built-in precision band-gap reference provides accurate receiver thresholds and improved noise immunity
- Compatible with IEEE Futurebus+ or proprietary BTL backplanes
- Each BTL driver has a dedicated Bus GND for a signal return
- Controlled output ramp and multiple GND pins minimize ground bounce

- Glitch-free power up/power down operation
- Low I_{CC} current
- Tight output skew
- Supports live insertion
- Pins for the optional JTAG boundary scan function are provided
- High density packaging in plastic Quad Flatpack
- 5V compatible I/O on A-port

DESCRIPTION

The FBL2031 is a 9-bit latched/registered transceiver featuring a latched, registered or pass-thru mode in either the A-to-B or B-to-A direction.

The FBL2031 is intended to provide the electrical interface to a high performance wired-OR bus.

QUICK REFERENCE DATA

SYMBOL	PARAMET	ER	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Bn		2.7	ns
t _{PLH} t _{PHL}	Propagation delay Bn to An		4.4 4.2	ns
Co	Output capacitance (BO - Bn only)		6	pF
I _{OL}	Output current (BO - Bn only)		100	mA
		Aln to Bn (outputs Low or High)	11	
I _{CC}	Supply current	Bn to AOn (outputs Low)	22	mA
		Bn to AOn (outputs High)	18	

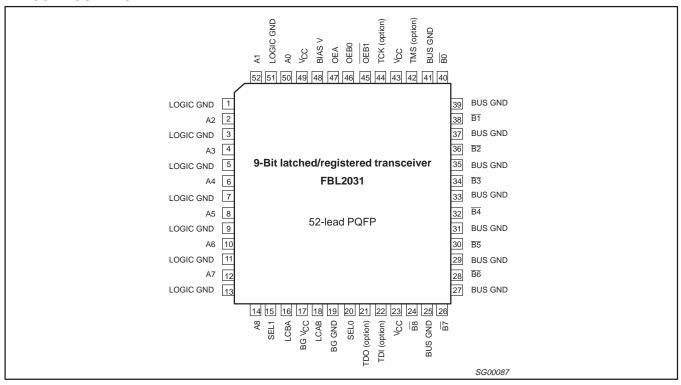
ORDERING INFORMATION

	PACKAGE	V _{CC} = 3.3V±10%; T _{amb} = -40°C to +85°C	DWG No.
Ī	52-pin Plastic Quad Flat Pack (PQFP)	FBL2031BB	SOT379-1

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PIN CONFIGURATION



PIN DESCRIPTION

SYMBOL	PIN NUMBER	TYPE	NAME AND FUNCTION
A0 – A8	50, 52, 2, 4, 6, 8, 10, 12, 14	I/O	BiCMOS data inputs/3-State outputs (TTL)
B0 – B8	40, 38, 36, 34, 32, 30, 28, 26, 24	I/O	Data inputs/Open Collector outputs, High current drive (BTL)
OEB0	46	Input	Enables the B outputs when High
OEB1	45	Input	Enables the B outputs when Low
OEA	47	Input	Enables the A outputs when High
BUS GND	25, 27, 29, 31, 33, 35, 37, 39, 41	GND	Bus ground (0V)
LOGIC GND	51, 1, 3, 5, 7, 9, 11, 13	GND	Logic ground (0V)
V_{CC}	23, 43, 49	Power	Positive supply voltage
BIAS V	48	Power	Live insertion pre-bias pin
BG V _{CC}	17	Power	Band Gap threshold voltage reference
BG GND	19	GND	Band Gap threshold voltage reference ground
SEL0	20	Input	Mode select
SEL1	15	Input	Mode select
LCAB	18	Input	A to B clock/latch enable (transparent latch when Low)
LCBA	16	Input	B to A clock/latch enable (transparent latch when Low)
TMS	42	Input	Test Mode Select (optional, if not implemented then no connect)
TCK	44	Input	Test Clock (optional, if not implemented then no connect)
TDI	22	Input	Test Data In (optional, if not implemented then no connect)
TDO	21	Output	Test Data Out (optional, if not implemented then shorted to TDI)

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DESCRIPTION

The TTL-level side (A port) has a common I/O. The common I/O, open collector B port operates at BTL signal levels. The logic element for data flow in each direction is controlled by two mode select inputs (SEL0 and SEL1). A "00" configures latches in both directions. A "10" configures thru mode in both directions. A "01" configures register mode in both directions. A "11" configures register mode in the A-to-B direction and latch mode in the B-to-A direction.

When configured in the buffer mode, the inverse of the input data appears at the output port. In the register mode, data is stored on the rising edge of the appropriate clock input (LCAB or LCBA). In the latch mode, clock pins serve as transparent-Low latch enables. Regardless of the mode, data is inverted from input to output.

The 3-State A port is enabled by asserting a High level on OEA. The B port has two output enables, OEB0 and OEB1. Only when OEB0 is High and OEB1 is Low is the output enabled.

When either OEB0 is Low or OEB1 is High, the B port is inactive and is pulled to the level of the pull-up voltage. New data can be entered in the register and latched modes or can be retained while the associated outputs are in 3-State (A port) or inactive (B port).

The B-port drivers are Low-capacitance open collectors with controlled ramp and are designed to sink 100mA. Precision band gap references on the B-port insure very good noise margins by limiting the switching threshold to a narrow region centered at 1.55V.

The B-port interfaces to "Backplane Transceiver Logic" (see the IEEE 1194.1 BTL standard). BTL features low power consumption by reducing voltage swing (1V p-p, between 1V and 2V) and reduced capacitive loading by placing an internal series diode on the

drivers. BTL also provides incident wave switching, a necessity for high performance backplanes.

Output clamps are provided on the BTL outputs to further reduce switching noise. The " V_{OH} " clamp reduces inductive ringing effects during a Low-to-High transition. The " V_{OH} " clamp is always active. The other clamp, the "trapped reflection" clamp, clamps out ringing below the BTL 0.5V V_{OL} level. This clamp remains active for approximately 100ns after a High-to-Low transition.

To support live insertion, OEB0 is held Low during power on/off cycles to insure glitch- free B port drivers. Proper bias for B port drivers during live insertion is provided by the BIAS V pin when at a 3.3V level while V_{CC} is Low. The BIAS V pin is a low current input which will reverse-bias the BTL driver series Schottky diode, and also bias the B port output pins to a voltage between 1.62V and 2.1V. This bias function is in accordance with IEEE BTL Standard 1194.1. If live insertion is not a requirement, the BIAS V pin should be tied to a V_{CC} pin.

The LOGIC GND and BUS GND pins are isolated inside the package to minimize noise coupling between the BTL and TTL sides. These pins should be tied to a common ground external to the package.

Each BTL driver has an associated BUS GND pin that acts as a signal return path and these BUS GND pins are internally isolated from each other. In the event of a ground return fault, a "hard" signal failure occurs instead of a pattern dependent error that may be infrequent and impossible to troubleshoot.

As with any high power device, thermal considerations are critical. It is recommended that airflow (300lfpm) and/or thermal mounting be used to ensure proper junction temperature.

PACKAGE THERMAL CHARACTERISTICS

PARAMETER	CONDITION	52-PIN PLASTIC QFP
θја	Still air	80°C/W
θја	300 Linear feet per minute air flow	58°C/W
θјс	Thermally mounted on one side to heat sink	20°C/W

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FUNCTION TABLE

MODE					INPUT	S				OUTI	PUTS
MODE	An	Bn*	OEB0	OEB1	OEA	LCAB	LCBA	SEL0	SEL1	An	Bn
An to Bn thru mode	L	_	Н	L	L	Х	Х	Н	L	input	H**
An to Bn thru mode	Н	_	Н	L	L	Х	Х	Н	L	input	L
An to Bn transparent latch	L	_	Н	L	L	L	Х	L	L	input	H**
An to bit transparent lateri	Н	_	Н	L	L	L	Х	L	L	input	L
An to Bn latch and read	I	_	Н	L	L	1	Х	L	L	input	H**
An to Bri lateri and read	h	_	Н	L	L	1	Х	L	L	input	L
Bn outputs latched and read (preconditioned latch)	Х	_	Н	L	Х	Н	Х	L	L	Х	latched data
An to Bn register	I	_	Н	L	L	1	Х	Х	Н	input	H**
An to Bn register	h	_	Н	L	L	1	Х	Х	Н	input	L
Bn to An thru mode		L	Disa	able	Н	Х	Х	Н	L	Н	input
Bit to Ari tiru mode	_	Н	Disa	able	Н	Х	Х	Н	L	L	input
		L	Disa	able	Н	Х	L	L	L	Н	input
Do to An transparent lotely	_	Н	Disa	able	Н	Х	L	L	L	L	input
Bn to An transparent latch	_	L	Disa	able	Н	Х	L	Н	Н	Н	input
		Н	Disa	able	Н	Х	L	Н	Н	L	input
		ı	Disa	able	Н	Х	1	L	L	Н	input
Bn to An latch and read	_	h	Disa	able	Н	Х	1	L	L	L	input
Bri to An lateri and read	_	- 1	Disa	able	Н	Х	1	Н	Н	Н	input
	_	h	Disa	able	Н	Х	1	Н	Н	L	input
An outputs latched and read		Х	Х	Х	Н	Х	Н	L	L	latched data	Х
(preconditioned latch)	_	Х	Х	Х	Н	Х	Н	Н	Н	latched data	Х
Do to An acciptor		1	Disa	able	Н	Х	1	L	Н	Н	input
Bn to An register	_	h	Disa	able	Н	Х	1	L	Н	L	input
Disable De cuteute	Х	Х	L	Х	Х	Х	Х	Х	Х	Х	H**
Disable Bn outputs	Х	Х	Х	Н	Х	Х	Х	Х	Х	Х	H**
Disable An outputs	Х	Х	Х	Х	L	Х	Х	Х	Х	Z	Х

FUNCTION SELECT TABLE

MODE SELECTED	SEL0	SEL1
Thru mode	Н	L
Register mode (An to Bn)	X	Н
Latch mode (An to Bn)	L	L
Register mode (Bn to An)	L	Н
Lotch mode (Pr. to An)	L	L
Latch mode (Bn to An)	Н	Н

NOTES:

H = High voltage level

L = Low voltage level

= Low voltage level one set-up time prior to the Low-to-High

h = High voltage level one set-up time prior to the Low-to-High LCXX transition

X = Don't care

Z = High-impedance (OFF) state

— = Input not externally driven

↑ = Low-to-High transition

H** = Goes to level of pull-up voltage

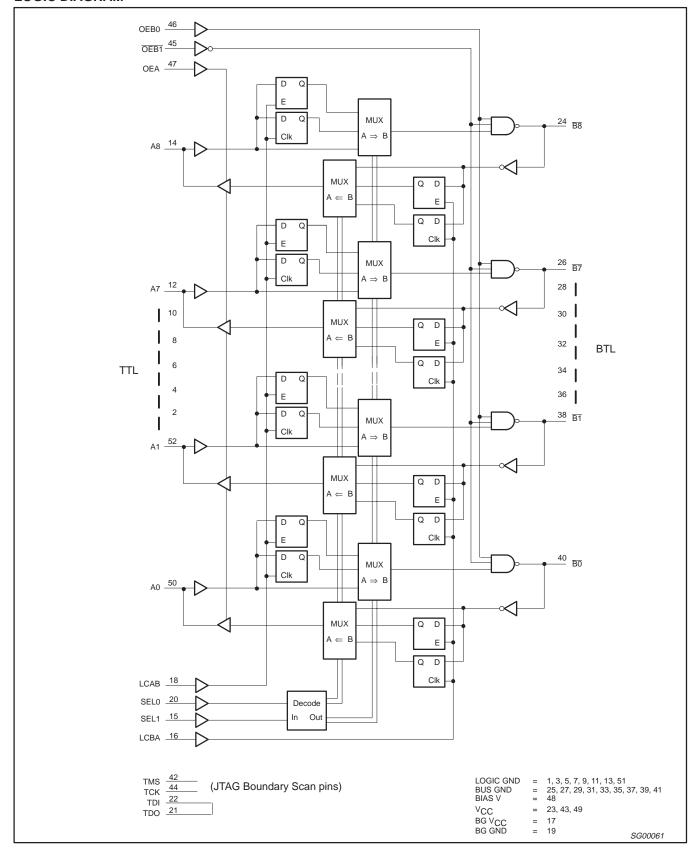
 $\overline{Bn}^* = Precaution should be taken to ensure B inputs do not float.$

If they do, they are equal to Low state.

Disable = OEB0 is Low or OEB1 is High.

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LOGIC DIAGRAM



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ABSOLUTE MAXIMUM RATINGS
Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.

SYMBOL	PARAMET	ER	RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +4.6	V
V	Input voltage	Al0 – Al6, OEB0, OEBn, OEAn	−0.5 to +7.0	V
V _{IN}	input voltage	<u>B0</u> – <u>B8</u>	−0.5 to +3.5	
I _{IN}	Input current	V _{IN} < 0	– 50	
V _{OUT}	Voltage applied to output in High output state		−0.5 to +7.0	V
1	Current applied to output in	AO0 – AO8	64, –64	mA
IOUT	Low output state/High output state	<u>B0</u> – <u>B8</u>	200	
T _{STG}	Storage temperature		-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMI	ETER	COMMERCIAL LIMITS $V_{CC} = 3.3V\pm10\%$; $T_{amb} = -40 \text{ to } +85^{\circ}\text{C}$			UNIT	
			MIN	TYP	MAX		
V _{CC}	Supply voltage	ipply voltage			3.6	V	
V	Llieb level input veltage	Except B0-B8	2.0			V	
V _{IH}	High-level input voltage	BO – B8	1.62	1.55		1	
V	Law law liment valle as	Except BO-B8	Except BO-B8			0.8	V
V _{IL}	Low-level input voltage	B0 – B8			1.47	1	
I _{IK}	Input clamp current	•			-18	mA	
I _{OH}	High-level output current	AO0 – AO8			-32	mA	
	Laurence and an extensión annual de	AO0 – AO8			+32	mA	
loL	Low-level output current	B0 – B8			100	1	
C _{OB}	Output capacitance on B port	-		6	7	pF	
T _{amb}	Operating free-air temperature range		0		+70	°C	

LIVE INSERTION SPECIFICATIONS

OVMDOL		DADAMETED		LIMITS		
SYMBOL		PARAMETER	MIN	TYP	MAX	UNIT
V _{BIASV}	Bias pin voltage	Voltage difference between the Bias voltage and V _{CC} after the PCB is plugged in.	-	-	0.5	V
	Bias pin (I _{BIASV}) input	V _{CC} = 0 V, Bias V = 3.6V			1.2	mA
BIASV	DC current	V _{CC} = 3.3V, Bias V = 3.6V			10	μΑ
V _{Bn}	Bus voltage during prebias	$\overline{B0} - \overline{B8} = 0$ V, Bias V = 3.3V	1.62		2.1	V
I _{LM}	Fall current during prebias	$\overline{B0} - \overline{B8} = 2V$, Bias V = 1.3 to 2.5V			1	μΑ
I _{HM}	Rise current during prebias	$\overline{B0} - \overline{B8} = 1V$, Bias V = 3 to 3.6V	-1			μΑ
I _{Bn} PEAK	Peak bus current during insertion	$V_{CC} = 0$ to 3.3V, $\overline{B0} - \overline{B8} = 0$ to 2.0V, Bias V = 2.7 to 3.6V, OEB0 = 0.8V, $t_r = 2$ ns			10	mA
1 055	Dower up ourront	V _{CC} = 0 to 3.3V, OEB0 = 0.8V			100	
I _{OL} OFF	Power up current	V _{CC} = 0 to 1.2V, OEB0 = 0 to 5V			100	μА
t _{GR}	Input glitch rejection	V _{CC} = 3.3V	1.0	1.35		ns

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range unless otherwise noted.

SYMBOL	DADAMET	ED.	TEST CONDITIONS		LIMITS		UNIT
STMBOL	PARAMET	EK	TEST CONDITIONS ¹	MIN	TYP ²	MAX	UNII
I _{OH}	High level output current	B0 – B8	$V_{CC} = MAX, V_{IL} = MAX, V_{OH} = 1.9V$			100	μΑ
1	Power-off output current	B0 – B8	$V_{CC} = 0V$, $V_{IL} = MAX$, $V_{OH} = 1.9V$			100	
I _{OFF}	Power-on output current	B0 - B0	$V_{CC} = 0V, V_{IL} = MAX, V_{OH} = 1.9V @ 85^{\circ}C$			300	μΑ
			V _{CC} = MIN to MAX	V _{CC} -0.2			V
V_{OH}	High-level output voltage	AO0 – AO8 ³	$V_{CC} = MIN; I_{OH} = -8mA$	2.4			V
			$V_{CC} = MIN; I_{OH} = -32mA$	2.0			V
		AO0 – AO8 ³	$V_{CC} = MIN; I_{OL} = 16mA$			0.4	V
V	Low-level output voltage	A00 = A08°	$V_{CC} = MIN; I_{OL} = 32mA$			0.5	V
V_{OL}	Low-level output voltage	B0 – B8	$V_{CC} = MIN, I_{OL} = 4mA$	0.5			V
			$V_{CC} = MIN, I_{OL} = 100mA$	0.75	1.0	1.20	\ \ \
V_{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK} = -18mA$		-0.85	-1.2	V
		Control pins	$V_{CC} = 3.6V$; $V_I = V_{CC}$ or GND			±1.0	
II	Input leakage current	Control/ AI0 – AI8	$V_{CC} = 0V \text{ or } 3.6V; V_I = 5.5V$			10	μΑ
		AI0 – AI8	$V_{CC} = 3.6V; V_I = V_{CC}$			1	
		Note 4	$V_{CC} = 3.6V; V_I = 0V$			- 5	
			$V_{CC} = MAX, V_I = 1.9V$			100	μΑ
I_{IH}	High-level input current	B0 – B8	$V_{CC} = MAX$, $V_I = 3.5V$, note 5	100			
			$V_{CC} = MAX, V_{I} = 3.75V @ -40^{\circ}C$	100			mA
I _{IL}	Low-level input current	B0 – B8	$V_{CC} = MAX, V_I = 0.75V$			-100	μΑ
I _{OZH}	Off-state output current	AO0 – AO8	$V_{CC} = MAX, V_O = 3V$			5	μΑ
I _{OZL}	Off-state output current	AO0 – AO8	$V_{CC} = MAX, V_O = 0.5V$			- 5	μΑ
		I _{CCH} B to A	V_{CC} = MAX, outputs High		18	32	mA
		I _{CCL} B to A	V _{CC} = MAX, outputs Low		22	37	mA
I_{CC}	Supply current (total)	I _{CCH} A to B	V_{CC} = MAX, outputs High		11	16	mA
		I _{CCL} A to B	$V_{CC} = MAX$, outputs Low		11	16	mA
		I _{CCZ}	V _{CC} = MAX		18	32	mA

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operation conditions for the applicable type.
- All typical values are at V_{CC} = 3.3V, T_A = 25°C.
 Due to test equipment limitations, actual test conditions are V_{IH} = 1.8V and V_{IL} = 1.3V for the B side.
 Unused pins are at V_{CC} or GND.
- 5. For B port input voltage between 3 and 5 volt; I_{IH} will be greater than 100mA but the part will continue to function normally (clamping circuit is active). This is not a tested condition.

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AC ELECTRICAL CHARACTERISTICS

				в то	A SPECI	FICATIONS		
SYMBOL	PARAMETER	TEST CONDITION		_{mb} = +25° / _{CC} = 3.3\			0 to +85°C, 3V±10%,	UNIT
			MIN	TYP	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	Waveform 4	120	150				MHz
t _{PLH} t _{PHL}	Propagation delay (thru mode) Bn to An	Waveform 1, 2	2.8 3.0	4.3 4.5	5.9 6.0	2.2 2.6	6.8 7.3	ns
t _{PLH} t _{PHL}	Propagation delay (transparent latch) Bn to An	Waveform 1, 2	2.8 3.4	4.9 5.0	7.0 6.6	1.8 2.8	8.4 7.8	ns
t _{PLH} t _{PHL}	Propagation delay LCBA to An (latch)	Waveform 1, 2	7.7 7.5	10.2 10.1	13.0 12.9	6.1 6.1	15.6 15.4	ns
t _{PLH} t _{PHL}	Propagation delay LCBA to An (register)	Waveform 1, 2	2.7 3.0	4.2 4.5	5.7 6.1	2.1 2.4	6.7 6.9	ns
t _{PLH} t _{PHL}	Propagation delay SEL0 or SEL1 to An (inverting)	Waveform 1, 2	2.9 1.9	5.8 5.8	9.1 10.4	2.2 1.2	10.5 11.6	ns
t _{PLH} t _{PHL}	Propagation delay SEL0 or SEL1 to An (non-inverting)	Waveform 1, 2	2.0 2.8	5.9 5.6	10.3 8.8	1.4 2.2	12.3 10.0	ns
t _{PZH} t _{PHZ}	Output enable time from High or Low OEA to An	Waveform 5, 6	3.0 4.0	4.4 5.6	5.7 7.3	2.6 3.2	6.6 8.3	ns
t _{PZL} t _{PLZ}	Output disable time to High or Low OEA to An	Waveform 5, 6	2.6 1.4	4.0 2.6	5.4 3.7	2.1 1.0	6.0 4.4	ns
t _{TLH} t _{THL}	Output transition time, An Port 10% to 90%, 90% to 10%	Test Circuit and Waveforms				0.2 0.1	2.0 1.2	ns
t _{SK} (o)	Output to output skew for multiple channels ¹	Waveform 3		0.5	1.0		1.5	ns
t _{SK} (p)	Pulse skew ² t _{PHL} - t _{PLH} _{MAX}	Waveform 2		0.5	1.0		1.5	ns

NOTES:

It_{PN}actual – t_{PM}actual | for any data input to output path compared to any other data input to output path where N and M are either LH or HL. Skew times are valid only under same test conditions (temperature, V_{CC}, loading, etc.). t_{SK} (0) compares t_{PLH} on a given path to t_{PLH} on any other path or compares t_{PHL} on a given path to t_{PHL} on any other path.
 t_{SK}(p) is used to quantify duty cycle characteristics. In essence it compares the input signal duty cycle to the corresponding output signal

duty cycle (50MHz input frequency and 50% duty cycle, tested on data paths only).

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AC ELECTRICAL CHARACTERISTICS

			Α	A TO B 9 Ω LOAD			TONS	
SYMBOL	PARAMETER	TEST CONDITION	T _{amb} = +25°C, V _{CC} = 3.3V,			$T_{amb} = -40$ $V_{CC} = 3$.	UNIT	
			MIN	TYP	MAX	MIN	MAX	1
t _{PLH} t _{PHL}	Propagation delay (thru latch) An to Bn	Waveform 1, 2	1.4 1.3	2.6 2.5	3.8 3.8	1.0 1.0	4.9 4.2	ns
t _{PLH} t _{PHL}	Propagation delay (transparent latch) An to Bn	Waveform 1, 2	1.7 2.0	2.9 3.5	4.2 5.0	1.0 1.5	5.4 5.7	ns
t _{PLH} t _{PHL}	Propagation delay LCAB to Bn (latch)	Waveform 1, 2	8.8 8.4	11.6 11.0	14.5 13.7	6.7 6.7	17.9 16.6	ns
t _{PLH} t _{PHL}	Propagation delay LCAB to Bn (register)	Waveform 1, 2	2.3 2.5	3.6 4.0	5.0 5.4	1.4 1.9	6.2 6.4	ns
t _{PLH} t _{PHL}	Propagation delay SEL0 or SEL1 to Bn (inverting)	Waveform 1, 2	2.3 1.3	3.8 4.8	5.5 8.8	1.2 1.0	7.0 9.6	ns
t _{PLH} t _{PHL}	Propagation delay SEL0 or SEL1 to Bn (non-inverting)	Waveform 1, 2	2.0 2.6	4.4 4.3	7.2 6.1	1.1 1.7	8.5 7.6	ns
t _{PLH} t _{PHL}	OEBn to Bn	Waveform 1, 2	1.2 1.9	2.9 3.3	4.8 4.7	1.0 1.2	5.8 6.4	ns
t _{TLH} t _{THL}	Output transition time, Bn Port (1.3V to 1.8V)	Test Circuit and Waveforms				1.2 0.4	3.0 1.5	ns
t _{SK} (o)	Output to output skew for multiple channels ¹	Waveform 3		0.4	1.0		2.0	ns
t _{SK} (p)	Pulse skew ² t _{PHL} - t _{PLH} _{MAX}	Waveform 2		0.3	1.0		1.5	ns

It_{PN}actual – t_{PM}actual | for any data input to output path compared to any other data input to output path where N and M are either LH or HL. Skew times are valid only under same test conditions (temperature, V_{CC}, loading, etc.). t_{SK} (0) compares t_{PLH} on a given path to t_{PLH} on any other path or compares t_{PH} on a given path to t_{PHL} on any other path.
 t_{SK}(p) is used to quantify duty cycle characteristics. In essence it compares the input signal duty cycle to the corresponding output signal duty cycle (50MHz input frequency and 50% duty cycle, tested on data paths only).

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AC ELECTRICAL CHARACTERISTICS

			A T	OB 16.	5 Ω LOAD	SPECIFICA	ATIONS	
SYMBOL	PARAMETER	TEST CONDITION	T _{ai}	_{mb} = +25° / _{CC} = 3.3\	C, /,	$T_{amb} = -40$ $V_{CC} = 3$.	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay (thru latch) An to Bn	Waveform 1, 2	1.4 1.2	2.7 2.4	3.9 3.6	1.0 1.0	5.0 4.0	ns
t _{PLH} t _{PHL}	Propagation delay (transparent latch) An to Bn	Waveform 1, 2	1.8 2.0	3.0 3.2	4.2 4.7	1.0 1.4	5.6 5.5	ns
t _{PLH} t _{PHL}	Propagation delay LCAB to Bn (latch)	Waveform 1, 2	8.6 8.0	11.4 10.6	14.2 13.3	6.5 6.4	17.5 16.1	ns
t _{PLH} t _{PHL}	Propagation delay LCAB to Bn (register)	Waveform 1, 2	2.2 2.3	3.5 3.7	4.8 5.1	1.2 1.7	6.1 5.9	ns
t _{PLH} t _{PHL}	Propagation delay SEL0 or SEL1 to Bn (inverting)	Waveform 1, 2	2.6 1.4	4.5 4.4	6.7 7.7	1.5 1.1	8.1 8.4	ns
t _{PLH} t _{PHL}	Propagation delay SEL0 or SEL1 to Bn (non-inverting)	Waveform 1, 2	2.2 2.3	4.5 4.0	6.9 5.8	1.4 1.5	8.2 6.9	ns
t _{PLH} t _{PHL}	OEB0 to Bn	Waveform 1, 2	1.8 1.7	3.1 2.9	4.4 4.2	1.0 1.0	5.8 6.0	ns
t _{TLH} t _{THL}	Output transition time, Bn Port (1.3V to 1.8V)	Test Circuit and Waveforms				1.2 0.4	3.0 1.5	ns
t _{SK} (o)	Output to output skew for multiple channels ¹	Waveform 3		0.5	1.0		2.0	ns
t _{SK} (p)	Pulse skew ² t _{PHL} - t _{PLH} _{MAX}	Waveform 2		0.5	1.0		1.5	ns

It_{PN}actual – t_{PM}actual | for any data input to output path compared to any other data input to output path where N and M are either LH or HL. Skew times are valid only under same test conditions (temperature, V_{CC}, loading, etc.). t_{SK} (0) compares t_{PLH} on a given path to t_{PLH} on any other path or compares t_{PH} on a given path to t_{PHL} on any other path.
 t_{SK}(p) is used to quantify duty cycle characteristics. In essence it compares the input signal duty cycle to the corresponding output signal duty cycle (50MHz input frequency and 50% duty cycle, tested on data paths only).

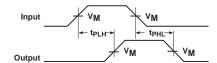
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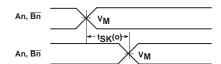
AC SETUP REQUIREMENTS (Commercial)

				LIM	IITS	
SYMPOL	PARAMETER	TEST	T _{amb} = +25°C	C, V _{CC} = 3.3V,	$T_{amb} = -40 \text{ to } +85^{\circ}\text{C}, \ V_{CC} = 3.3\text{V} \pm 10\%,$	UNIT
SYMBOL	PARAMETER	CONDITION	C _L :	I		
			MIN	TYP	MIN	
t _s (H) t _s (L)	Setup time An to LCAB	Waveform 4	1.3 1.3		1.5 1.5	ns
t _h (H) t _h (L)	Hold time An to LCAB	Waveform 4	1.0 1.0		1.0 1.0	ns
t _S (H) t _S (L)	Setup time Bn to LCBA	Waveform 4	5.0 4.0		6.0 4.5	ns
t _h (H) t _h (L)	Hold time Bn to LCBA	Waveform 4	0.0 0.0		0.0 0.0	ns
t _w (H) t _w (L)	Pulse width, High or Low LCAB or LCBA	Waveform 4	3.0 3.0		3.0 3.0	ns

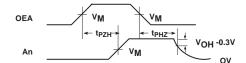
AC WAVEFORMS



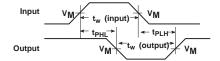
Waveform 1. Propagation Delay for Data or Output Enable to Output



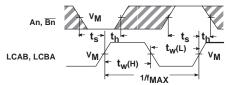
Waveform 3. Output to Output Skew



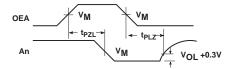
Waveform 5. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 2. Propagation Delay for Data or Output Enable to Output



Waveform 4. Setup and Hold Times, Pulse Widths and Maximum Frequency



Waveform 6. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

NOTE: V_M = 1.55V for \overline{Bn} , V_M = 1.5V for all others.

The shaded areas indicate when the input is permitted to change for predictable output performance.

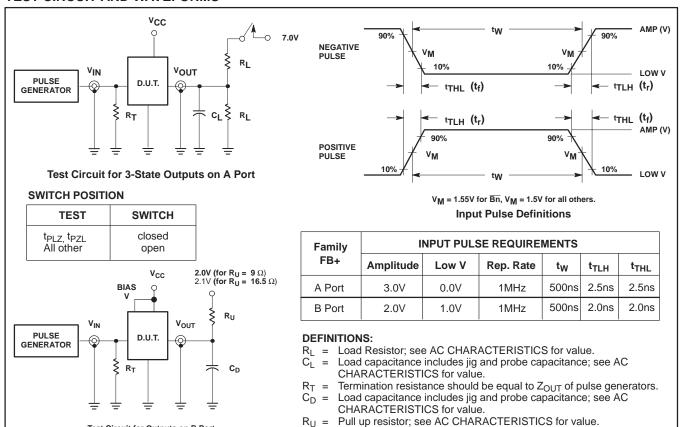
SG00062

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TEST CIRCUIT AND WAVEFORMS



2000 Apr 18 13

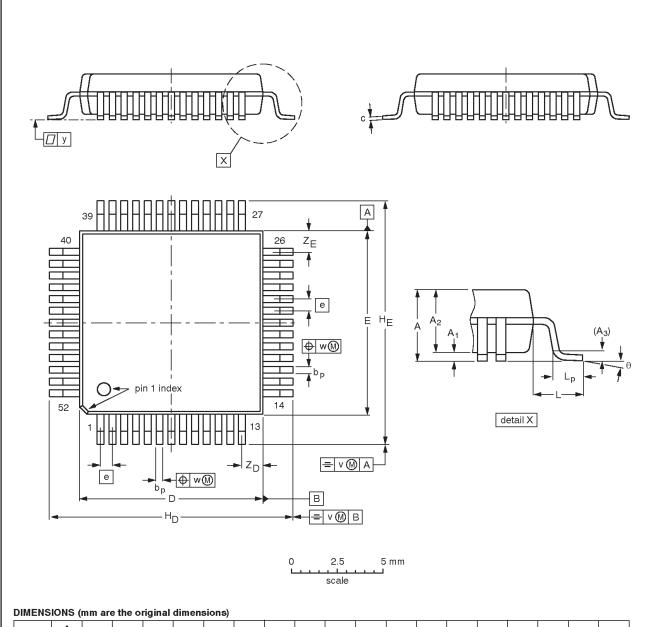
Test Circuit for Outputs on B Port

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QFP52: plastic quad flat package; 52 leads (lead length 1.6 mm); body 10 x 10 x 2.0 mm

SOT379-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	e	H _D	HE	L	Lp	v	w	У	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	2.45	0.45 0.25	2.10 1.95	0.25	0.38 0.22	0.23 0.13	10.1 9.9	10.1 9.9	0.65	13.45 12.95	13.45 12.95	1.60	0.95 0.65	0.20	0.12	0.10	1.24 0.95	1.24 0.95	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT379-1	135E04	MS-022			-99-12-27- 00-01-19

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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